

PIN-TO-PIN COMPATIBLE FAMILIES



	Aquila	Verdin	Lino	SMARC	OSM
Form Factor	Proprietary	Proprietary	Proprietary	Industry Standard	Industry Standard
SoM Physical Size	85.0 x 55.0 mm	69.6 x 35.0 mm	30 x 30 mm	82.0 x 50.0 mm	30 x 30 mm (S) 45 x 45 mm (L)
SoM Connector	Board to Board	Edge Connector (SODIMM)	Board to Board	Edge Connector (MXM)	Solderable (LGA Pads)
Pin Count	400 pins	260 pins	200 pins	314 pins	332 pins (S) 662 pins (L)
Power Envelope (TDP)	Up to 30W	Up to 12W	Up to 5W	Up to 15W	TBD
Performance	Higher-End	Mid-Range	Lower-End	Mid-Range	Lower to Mid-Range
Cortex-A Cores	6 to 8x	1 to 6x	1 to 2x	2 to 6x	1 to 2x
RAM Availability	Up to 32GB	Up to 8GB	Up to 2GB	Up to 8GB	Up to 2GB
Keywords	<ul style="list-style-type: none"> High CPU, GPU, NPU Performance Wide Interface Availability Advanced Robustness 	<ul style="list-style-type: none"> General Purpose Compact Design Easy Carrier Board Development 	<ul style="list-style-type: none"> Ultra-Compact Footprint High-Volumes (5k to 50k/yr ideal) 	<ul style="list-style-type: none"> SMARC Standard Second-Sourcing Availability 	<ul style="list-style-type: none"> Ultra-Compact Footprint Solderable Module High-Volumes (10k to 250k/yr ideal)
Perfect for	<ul style="list-style-type: none"> High-End AI Applications Migrating from x86 to ARM NVIDIA Alternatives 	<ul style="list-style-type: none"> Scalable Product Platforms High Value/Cost Optimization 	<ul style="list-style-type: none"> Space-Constrained Designs 	<ul style="list-style-type: none"> Multi-Vendor Ecosystems Projects Requiring Second Sourcing 	<ul style="list-style-type: none"> Solder-Down Designs Very High Project Volumes

PIN-TO-PIN COMPATIBLE FAMILIES

